

ABSTRACT OF THE DISCLOSURE

In a film lamination apparatus and method, there is no one-side contact of a pressing roller that presses a film to be laminated. The film is
5 laminated using a rotatable pressing roller having a heater incorporated therein. The pressing roller is pressed onto the film placed on a semiconductor substrate while generating heat by the heater inside the pressing roller. The pressing roller is rolled
10 on the film so as to laminate the film on the semiconductor substrate by partially heating the film by the pressing roller while moving the pressing roller.